# *User's Guide Input Resistance Error for Current Sense Amplifiers*



*Peter Iliya*

#### **ABSTRACT**

Resistive loading at the input pin (IN+ and IN-) and bias or reference pins (REF) of current sense amplifiers (CSA) can create significant error ( $e_{FXT}$ ) in the output measurement; however, this error can be calculated and managed to acceptable levels for low-accuracy, low-cost, or small form factor applications.

In this guide, CSAs with resistance at input and reference pins are designed, and tested over temperature. Two types of devices are tested. One device is a standard linear CSA (INA185) and the other device is a capacitively-coupled, high-input impedance CSA (INA191). Both devices are tested with and without input resistance over temperature to determine and verify the error generated solely from the input resistance.

# **Table of Contents**



# **Trademarks**

All trademarks are the property of their respective owners.

# <span id="page-1-0"></span>**1 Introduction**

Most current sense amplifiers (CSA) have input resistances much lower than similarly closed-loop instrumentation (in-amps) and difference amplifiers. This is primarily because of the non-isolated connections to the inputs pin, but also due to the input bias stage in between input pins. Thus, CSAs ideally should have little to no external input resistances (R<sub>EXT</sub> < 10Ω) at input pins; however, certain applications may require higher  $R_{EXT}$  and thus it becomes crucial to understand and calculate worst-case error to see if circuit still meet system requirements.

In recent years, capacitively-coupled input current sense amplifiers (for example, INA190 or INA191) can present much higher effective differential resistances in the range to  $2MΩ$  to  $5MΩ$  over temperature.



**Over Temperature**

These devices can easily measure lower current in the micro-Amps range and also maintain high accuracy with larger input resistors. Note that capacitively-coupled input amplifiers often require some differential input capacitance at the input pins whenever significant external impedance is present. This is to help provide charge to internal switching capacitors.

The other important input loading resistance for most CSAs and difference amplifiers is the reference voltage source resistance  $(R<sub>EXT3</sub>)$ . Reference (REF) pins allow the output of bidirectional CSAs to be biased to voltage when the measuring 0-V differentially. System design cost and complexity can be reduced by simply driving REF pins with a resistor divider as opposed to a low-impedance source. However, all error sources and loss of dynamic range must be considered and bounded. For a detailed analysis of error generated from loading REF pins, refer to *[Driving Voltage Reference Pins of Current-Sensing Amplifiers](https://www.ti.com/lit/pdf/sboa551)*, application note.

Overall, higher input impedance devices can be more accurate with external loading; however with only a few specifications of process variation, a system designer using a CSA with  $R_{FXT}$  >10Ω can achieve manageable error targets in low-accuracy, but low-cost and small PCB systems. This document shows how to calculate the bounds of this input resistance over temperature. In many cases a one-point, offset calibration is most practical.

<span id="page-2-0"></span>

# **2 CSAs and Input Bias Stage**

The input bias stage allows CSAs to operate with supply voltages  $(V<sub>S</sub>)$  independent of input common-mode voltage ( $V_{CM}$ ). For most devices, the input bias stage has a resistance ( $R_{BIAS}$ ) in between input pins ranging from 2kΩ to 72kΩ. This resistances creates an effective differential bias current (I<sub>B, Differential</sub>) that is proportional to the input differential shunt voltage.



**Figure 2-1. Simplified Equivalent Models of Single Stage Current Sense Amplifier With Input Bias Stage**

Within the input bias stage is circuitry that monitors the  $V_{CM}$  to appropriately turn on a bias current ( $I_{B, CM\,ON}$ ). This usually occurs when  $V_{CM}$  exceeds  $V_S$  or some proportional value (check data sheet). For example with the single-stage CSA, INA185, a large jump in total input bias current occurs when  $V_{CM}$  exceeds the 5V supply voltage.



**Figure 2-2. Input Bias Current vs Input Common-Mode Voltage for INA185**

Aside from this shift, the total  $I_{B, CM}$  is the general leakage current ( $I_{B, Leakage}$ ) from bus voltage at input pins to the reference voltage at REF pin. Thus the total input bias current for each input pin is the summation of common-mode leakage from bus to reference,  $I_{B, CM ON}$ , and the differential current through  $R_{BIAS}$ .

<span id="page-3-0"></span>

(1)

 $I_{B, \; Leakage}$  =  $\frac{V_{CM} - V_{REF/BIAS}}{R_{INT} ~+~ R_{FB} +~ R_{FB}}$  $R_{INT}$  +  $R_{FB}$  +  $R_{EXT}$  $I_{B, Total}$  =  $I_{B, Leakage}$  +  $I_{B, Differential}$  +  $I_{B, CM ON}$ 

Note for two-stage CSAs, the  $I_{B, Leakage}$  is determined by difference between  $V_{CM}$  and the internal bias voltage  $(V<sub>CM2</sub>)$  in between first and second stage; however, please defer to the input bias current data plots in data sheets as current pathway can be more complex.

Understanding input bias currents is important as input bias determine offset error from external input resistance  $(V_{OS, EXT})$ .

# **3 CSA and Gain Error Factor**

The typical device gain shown in data sheets for a single-stage, differential CSA is simply the matched ratio of  $R_{FB}$  over  $R_{INT}$  as shown in Equation 2.

$$
Gain_{typical} = {^{RFB, \, typical}}/{R_{INT, \, typical}}
$$
 (2)

When using input resistors ( $R_{EXTERNAL}$  or  $R_{EXT}$ ), the total shunt voltage gain (Gain<sub>TOTAL</sub>) becomes predictably attenuated due to a Gain Error Factor (GEF) that is less than 1. This new attenuated gain can be theoretically calculated using Equation 3. This total shunt voltage gain is now the new typical gain of the circuit. Note equations for a device's GEF are usually provided in data sheet.

$$
Gain_{Total, typical} = Gain_{typical} \times GEF_{Typical}
$$
\n(3)

When introducing an input GEF, there is a new way to reference input offset voltages. Normally, the initial offset error specified in the data sheet ( $V_{OSI}$ ) is referred to the input (RTI), but to refer it to the shunt (RTS), you need to divide by the GEF. This also applies to the derivation of  $V_{OS, EXT RTI}$  shown at end of document.



### **Figure 3-1. RTI (Referred-to-input) and RTS (Referred-to-shunt) for CSA with Input Resistors**

```
V_{OS \, EXT \, RTS} = V_{OS \, EXT \, RTI}/_{GET}V_{OSI\,RTS} = \frac{V_{OSI\,RTI}}{V_{GEF}}
```
(4)

<span id="page-4-0"></span>

Once the new typical total gain is determined, the designer can shift (calibrate) the shunt voltage gain in system hardware or software. However, there can be a significant increase in gain error variation ( $E_{G, EXT}$ ) over system population due to the fact that internal resistors are designed to achieve accurate ratios (Device Gain =  $R_{FB}$ )  $R<sub>INT</sub>$ , not accurate absolute values.

For most CSAs, conservative evaluations put the absolute process variation (PV) of these resistors at ±20% and with temperature coefficients (PV\_TC) of ±30 ppm/°C. These are based upon the specifications of the process technology. Furthermore, error analysis is simplified by the fact that all internal resistors for a single device can inherently have the same PV and PV\_TC. With these PV specifications defined, a designer can calculate the bounds of external resistance loading error ( $e_{EXT}$ ).

# **4 Applications for Resistance at Input Pins of Current Sense Amplifiers**

Table 4-1 is a non-comprehensive list of applications and reasons why a system needs resistors at the input pins (IN+ and IN-) for a current sense amplifier.



### **Table 4-1. Applications for Using Current Sense Amplifier (CSA) with Input Resistors**

For Figure 4-1, the input filter cutoff frequency is  $f_{C,differential} = 1 / (2 \times Pl \times 2 \times R_{FILTER} \times C_{DIFF}}$ .



## **Figure 4-1. Current Sense Amplifier with Input Differential Filter**

For [Figure 4-2](#page-5-0), the input filter cutoff frequency is  $f_{C\text{,differential}} = 1 / (2 \times \text{Pl} \times 2 \times \text{R<sub>FILTER</sub> \times (C<sub>DIF</sub> + C<sub>CM</sub> / 2)).$ 



<span id="page-5-0"></span>

**Figure 4-2. Current Sense Amplifier With Input** 



**Common-Mode Filter Figure 4-3. Current Sense Amplifier With Input Protection Diode Clamps and Resistors**

## **4.1 Input Resistance Design Considerations**

Whenever using large input resistance (>10- $\Omega$ ) at CSA input pins, the system engineer can determine what the maximum allowable errors are at the minimum and maximum sense current levels, calculate the theoretical error with input resistors, and then make following considerations:

- 1. Is the new (attenuated) typical circuit gain sufficient?
- 2. Is the new gain error range within maximum allowable error over temperature?
- 3. Is the new offset error within maximum allowable error at  $I_{LOAD-MIN}$ ?
- 4. If error at  $I_{LOAD-MIN}$  is too high, can offset error be calibrated out with 1-point calibration?
	- a. Can a small  $V_{REF}$  (approximately 100mV) be used to simplify this calibration?
		- b. Is there enough dynamic range left when providing this  $V_{REF}$ ?
- 5. If the error from input resistance is still too high, can a high-input impedance device such as the INA190, INA191, or INA186 be used instead?

# **5 Applications for Input Resistance at Reference Pins of Current Sense Amplifiers**

## **5.1 Bidirectional CSA and Applications**

As an overview, any CSA that has a reference (REF) pin is considered bidirectional. The majority of applications that require a bidirectional CSA are shown in Table 5-1.



#### **Table 5-1. Applications that Require CSA Reference Pin**

While the primary purpose of biasing a CSA output is to measure bidirectional current, another important application is the fast acquisition of unidirectional pulse-width modulated (PWM) currents that start at 0A. When any amplifier is starting from 0mV input or lower and  $V_{REF}=0$ , then  $V_{OUT}$  is starting the response in saturation, which can cause output distortion, overload recovery delays, and slow down amplifier response and settling times. Simply providing a small reference voltage (usually ≥ 100mV) to position the output into linear operating region can restore the device BW into specification at the expense of losing some output dynamic range.

The other important purpose for providing a reference voltage is to simplify a one-point offset calibration. One-point offset calibration procedures require one point of data and the easiest data point to use is when signal current = 0A (load disabled). Negating offset error can significantly reduce low current sensing error and thus increase accurate dynamic range.

A host's single-ended ADC can record and store into memory  $V_{\text{OUT}}$  when load is off to calibrate out the tolerance of  $V_{REF}$  as well as device offset.

<span id="page-6-0"></span>A differential or pseudo-difference ADC can measure the output differentially ( $V_{OUT, differential}$ ), which is  $V_{OUT}$ with respect to the reference pin ( $V_{REF}$ ). This allows system to negate error in  $V_{REF}$  without needing to perform calibration because the resulting output measurement is the differential input multiplied by device gain. Error can be further minimized by performing a one-point calibration to calibrate the amplifier's offset.

# **5.2 Driving CSA Reference Pin With High-Resistance Source Voltage**

Normally, the reference pins are driven with low-impedance (< 10Ω) voltage sources or buffers to prevent loading down the resistor feedback network. However, certain system applications can require external loading resistance as listed in Table 5-2.

### **Table 5-2. Applications for Driving Reference Pin with High-Resistance Source Voltage**



Input resistance at device reference/bias pins can create significant single-ended error, but much of the error can be negated simply by measuring the differential output voltage ( $V_{\text{OUT}}$  differential), which is  $V_{\text{OUT}}$  with respect to the reference pin  $(V_{REF}$ , and/or performing a one-point system calibration. For a detailed analysis of the error generated from loading REF pins, refer to this *[Driving Voltage Reference Pins of Current-Sensing Amplifiers](https://www.ti.com/lit/pdf/sboa551)*  application note.

# **5.3 Input Resistance at Reference Pin Design Considerations**

Whenever using large input resistance (>10-Ω) at CSA reference pins, the system engineer can follow [Section 8](#page-16-0)  and make following considerations:

- 1. Is the reduced dynamic range large enough for required system dynamic range?
- 2. If ADC must be single-ended, can system perform 1-point offset calibration to negate  $V_{REF}$  tolerance and CSA input offset?
- 3. Can ADC make a differential/pseudo-differential measurement to negate  $V_{REF}$  variation without need for 1-point calibration?
	- a. Furthermore, can differential ADC and system perform a 1-point calibration to negate CSA input offset error?
- 4. How much can the input V<sub>CM</sub> change? For single-stage CSAs, as V<sub>CM</sub> changes so can the effective V<sub>REF</sub> voltage since current can flow from  $V_{CM}$  through input pins and to the REF pin. Thus, a fluctuating  $V_{CM}$  of even a few volts can further reduce dynamic range.

# **6 Design Procedure and Error Calculation for External Input Resistance on CSA**

When using a single-stage, difference CSA and determining input external resistance error, follow the procedure below.

- 1. Determine what the system's maximum and minimum ambient temperatures is and use [Equation 6](#page-7-0) to determine worst-case temperature change from the standard 25°C testing condition ( $\Delta T_{A, MAX}$ ).
- 2. Using data sheet information determine the typical (or nominal) values of the internal resistors for CSA's first stage ( $R_{BIAS}$ ,  $R_{INT}$ , and  $R_{FB}$ ).
	- a. Note that typical process values assume  $T_A = 25^{\circ}$ C and PV = 0%
- 3. Also identify values for bias turn on currents  $(I_{B, CM ON})$  and input offset current  $(I_{OS})$ .
	- a.  $I_{B, CM ON}$  can be determined by calculating the vertical shift in  $I_{B, CM}$  as shown in [Figure 2-2](#page-2-0).
	- b. Assuming ±20% variation in this values is a conservative approximation.
- 4. Using [Equation 8](#page-8-0) and [Equation 3,](#page-3-0) calculate the new typical attenuated gain (Gain<sub>TOTAL, typical</sub>) assuming typical process variation (PV = 0%) for R<sub>BIAS</sub>, R<sub>INT</sub>, and R<sub>FB</sub>, nominal tolerance ( $e_{REXT} = 0$ %) for R<sub>EXT</sub>, and nominal device gain error ( $E_G = 0\%$ ).
	- a. Note: Equation for GEF is usually provided in the data sheet.
- 5. Calculate the worst-case maximum and minimum resistance values of all resistors using [Equation 7](#page-7-0) and [Equation 9](#page-8-0).



- <span id="page-7-0"></span>a. Note that the tolerance error for any internal resistance (e.g.,  $R_{FB}$ ) is the process variation (PV) value. Additionally, the temperature coefficient (TC) for any internal resistance is the process value's temperature coefficient (PV\_TC).
- b. Note for the calculation of  $R_{\text{INT}}$  with [Equation 9,](#page-8-0) incorporating the maximum device's internal gain error  $(E_{G, MAX})$  generates a very conservative total gain error approximation. However, given the statistical independence between resistor matching  $(E_G)$  and resistor tolerance (PV), it is also fair to simply let  $E_G = 0\%$ , but add  $E_{G, MAX}$  later during a final root sum square error calculation,

 $E_{G,\;Total}$  =  $\sqrt{E_{G,\;MAX}}^2$  +  $E_{G,\;EXT}^2$ .

- i. To simply calculate the gain error caused by the external resistors ( $E_{G, ET}$ ), set  $E_G = 0\%$  for equation [Equation 9.](#page-8-0)
- 6. Calculate the total maximum (positive) gain (Gain<sub>MAX</sub>) and minimum (negative) gain (Gain<sub>MIN</sub>) at 25° ( $\Delta T_A$  = 0°) using equation set [Equation 10](#page-8-0) where the inputs and conditions for function [Equation 8](#page-8-0) are noted.
	- a. Maximum gain occurs when:
		- i.  $R_{BIAS}$ ,  $R_{INT}$ , and  $R_{FB}$  are maximum (positive) tolerance and drift
		- ii.  $R_{\text{FXT}}$  is at minimum (negative) tolerance and drift
	- b. Minimum gain occurs when:
		- i.  $R_{B|AS}$ ,  $R_{INT}$ , and  $R_{FB}$  are minimum (negative) tolerance and drift
		- ii.  $R_{EXT}$  is at maximum (positive) tolerance and drift
- 7. Using equation set [Equation 11,](#page-8-0) calculate the new maximum and minimum gain errors at 25°C *relative to the new attenuated shunt voltage gain* determined in step 4.
- 8. Calculate maximum and minimum gains (Gain<sub>Total, MAX</sub> and Gain<sub>Total, MIN</sub>) at the maximum temperature swing  $(\Delta T_A = \Delta T_{A, MAX})$  using equation set [Equation 10.](#page-8-0)
	- a. Calculate the gain errors relative to the Gain<sub>Total, typical</sub> using [Equation 11](#page-8-0)
- 9. Calculate gain error drift E<sub>G, EXT drift</sub> in parts per million per degrees Celsius (ppm/°C) using equation [Equation 12.](#page-8-0)
	- a. Note that gain error drift cannot remain constant over process variation.
	- b. Note that these equations can use any two temperatures for  $T_{A1}$  and  $T_{A2}$ , although choosing them at 25°C and 25°C+ $\Delta T_{A, MAX}$  is most convenient given these gain errors have already been calculated.
- 10. Calculate the maximum (positive) offset ( $V_{OS,EXT, MAX RTI}$ ) and minimum (negative) possible offset (V<sub>OS\_EXT, MIN RTI</sub>) due to  $R_{EXT}$  at 25°C ( $\Delta T_A = 0^\circ$ ) using [Equation 13](#page-9-0) with conditions defined by [Equation 14](#page-9-0).
	- a. Using the same conditions, calculate the GEF using [Equation 16](#page-9-0) and convert RTI offsets into RTS using [Equation 4.](#page-3-0)
	- b. See [Section 11](#page-28-0) at end of this document on how this equation was derived.
- 11. Calculate the maximum (positive) offset ( $V_{OS,EXT, MAX RTI}$ ) and minimum (negative) possible offset (V<sub>OS\_EXT, MIN RTI</sub>) due to R<sub>EXT</sub> at maximum temperature swing ( $\Delta T_A = \Delta T_{A, MAX}$ ) using function [Equation](#page-9-0) [13](#page-9-0) with conditions defined by [Equation 14.](#page-9-0)
	- a. Using the same conditions, calculate the GEF using [Equation 16](#page-9-0)and convert RTI offsets into RTS using [Equation 4.](#page-3-0)
- 12. Calculate input offset drift due to  $R_{\text{EXT}}$  using [Equation 15](#page-9-0)
- 13. Calculate total system error

$$
a. \quad E_{Total} \quad =
$$

$$
\sqrt{E_{G,MAX}^2 + E_{G,EXT}^2 + (\frac{V_{OS, Device}}{V_{SHUNT}})^2 + (\frac{V_{OS,EXT}}{V_{SHUNT}})^2 + (\frac{V_{OS, DeviceDrift}}{V_{SHUNT}})^2 + (\frac{V_{OS,EXTDrift}}{V_{SHUNT}})^2}
$$

- b. Note that device's input offset ( $V_{OSI}$ ) and drift specification are referred to the input (RTI). Thus these values need to be referred to the shunt using [Equation 4](#page-3-0).
- c. If a one point calibration is performed, then offset components at 25°C can be removed.

# **Error Equations for Resistance at Input Pins of Single-Stage Current Sense Amplifier**

$$
\Delta T_{A,\;max} = \; MAX\{T_{A,\;high} - 25^{\circ}C, \; 25^{\circ}C - T_{A,\;low}\} \tag{6}
$$

$$
R_{MAX} = R_{NOMINAL} (1 \pm e_{tolerance}) (1 \pm \Delta T_{A,MAX} \times T C_R)
$$
 (7)

(5)

<span id="page-8-0"></span>
$$
GEF = \frac{\frac{R_{BIAS}}{2} \times R_{INT}}{\frac{R_{BIAS}}{2} \times R_{EXT} + \frac{R_{BIAS}}{2} \times R_{INT} + R_{EXT}}
$$
(8)

$$
R_{INT, MAX} = \frac{R_{FB, MAX}}{Gain_{Device, typical} \times (1 + E_{G, MAX})}
$$
\n
$$
R_{INT, MIN} = \frac{R_{FB, MIN}}{Gain_{Device, typical} \times (1 + E_{G, MIN})}
$$
\n
$$
\begin{pmatrix}\nPV & = maximum (e.g., +20\%) \\
PV\_TC & = maximum (e.g., +30\ ppm) \end{pmatrix}
$$
\n(9)

$$
GEF_{MAX} = GEF \begin{cases} e_{REXT} = \text{minimum} (e.g., -1\%) \\ TC_{REXT} = \text{minimum} (e.g., -50 \text{ ppm})^{\circ}C \\ E_G = \text{typical} (e.g., 0\%) \\ PV = \text{minimum} (e.g., -20\%) \\ PV = \text{minimum} (e.g., -30 \text{ ppm})^{\circ}C \end{cases}
$$
(10)  
\n
$$
GEF_{MIN} = GEF \begin{cases} e_{REXT} = \text{maximum} (e.g., +1\%) \\ e_{REXT} = \text{maximum} (e.g., +1\%) \\ TC_{REXT} = \text{maximum} (e.g., +50 \text{ ppm})^{\circ}C \end{cases}
$$
  
\n
$$
Gain_{Total, MAX} = \begin{pmatrix} 0 & \text{of } C \\ G & \text{of } C \end{pmatrix}
$$
  
\n
$$
Gain_{Total, MAX} = \begin{pmatrix} 0 & \text{of } C \\ G & \text{of } C \end{pmatrix}
$$
  
\n
$$
G_{MAX} = \begin{pmatrix} 0 & \text{of } C \\ G & \text{of } C \end{pmatrix}
$$

$$
Gain_{Total, MIN} = \left( Gain_{Device} = \frac{R_{FB}}{R_{INT}} \right) \times \left( GEF_{MIN} \right)
$$

$$
E_{G, \text{EXT} \text{MAX}} = \frac{Gain_{\text{Total}} - Gain_{\text{Total}}}{Gain_{\text{Total}} + typical}
$$
(11)  

$$
E_{G \text{EXT}, \text{MIN}} = \frac{Gain_{\text{Total}} - Gain_{\text{Total}}}{Gain_{\text{Total}} + typical}
$$

$$
E_{G\,Drift, \,EXT\,MAX} = \frac{E_{G, \,MAX\,T_{A,2}} - E_{G, \,MAX\,T_{A,1}}}{T_{A,2} - T_{A,1}} \times 10^6
$$
\n
$$
E_{G\,Drift, \,EXT\,MIN} = \frac{E_{G, \,MIN\,T_{A,2}} - E_{G, \,MIN\,T_{A,1}}}{T_{A,2} - T_{A,1}} \times 10^6
$$
\n
$$
(12)
$$

<span id="page-9-0"></span>

$$
V_{OS, EXTRTI} = \frac{\left(v_{REF} - v_{BUS}\right)\left(1 - c_{EV}\right) + I_{B,CMON}\left(R_{SH} + R_{EXT2} - R_{EXT}C_{EV}\right) - \frac{I_{OS}}{2}\left(R_{SH} + R_{EXT2} + R_{EXT1}C_{EV}\right)}{1 + \left(R_{SH} + R_{EXT2}\right)}
$$
\n
$$
C_{ev} = \frac{1 + \frac{R_{SH} + R_{EXT2}}{R_{FB} + R_{INT}}
$$
\n
$$
\frac{1 + \frac{R_{EH} + R_{EXT2}}{R_{FB} + R_{INT}}
$$
\n
$$
\frac{V_{B,CM ON} - V_{CM}}{V_{REF}} = \frac{V_{OS, EXTMAX}}{1 - \frac{1}{R_{EF}} + R_{INT}}
$$
\n
$$
V_{0SS, EXTMAX} = V_{OS,EXT}\left(\frac{1}{10S} - \frac{1}{10S}\right)
$$
\n
$$
V_{RET} = \frac{1}{1000}
$$
\n
$$
V_{S,EXT MAX} = V_{OS,EXT}\left(\frac{1}{10S} - \frac{1}{10S}\right)
$$
\n
$$
V_{S,EXT MIN} = V_{OS,EXT}\left(\frac{1}{10S} - \frac{1}{10S}\right)
$$
\n
$$
V_{S,EXT MIN} = \frac{V_{OS,EXTMAX at T_{A,2}} - V_{OS,EXTMAX at T_{A,1}}}{V_{A,2} - \frac{1}{10S}}
$$
\n
$$
V_{S,EXT Drift MAX} = \frac{V_{OS,EXTMAX at T_{A,2}} - V_{OS,EXTMAX at T_{A,1}}}{V_{A,2} - \frac{1}{10S}}
$$
\n
$$
V_{S,EXT Drift MIN} = \frac{V_{OS,EXTMAX at T_{A,2}} - V_{OS,EXTMAX at T_{A,1}}}{V_{A,2} - \frac{1}{10S}}
$$
\n
$$
V_{S,EXT Drift MIN} = \frac{V_{OS,EXTMAX at T_{A,2}} - V_{S,EXTMAX at T_{A,1}}}{V_{S,RT}} \tag{16}
$$

$$
\frac{V_{OS, \,EXT\,RTI}}{V_{SH}} = GEF = \frac{1}{\left(1 + \frac{R_{EXT2}}{R_{INT}}\right) + \frac{R_{EXT1} + R_{EXT2}}{R_B} - \frac{C_{EG}(R_{EXT1} - R_{EXT2})}{R_B}}
$$
  
\n
$$
V_{OS, \,EXT\,RTS} = \frac{V_{OS, \,EXT\,RTI}}{GEF}
$$

# <span id="page-10-0"></span>**6.1 Calculating eEXT for INA185A4 With 110Ω Input Resistors**

Use the previous equations to perform an analysis on a hypothetical circuit with the INA185A4 with 110Ω resistors  $(R<sub>FXT</sub>)$  at input pins. Consider the following circuit parameters:





Most of the fundamental circuit parameters needed are found in data sheet. However there is some calculation and estimation needed for  $I_{OS}$  and  $I_{B, CM\ ON}$ .

Typical  $I_{OS}$  is usually very small; however, this can increase for any ratio mismatch between the  $R_{BIAS}/2$  resistors seen in [Figure 2-1](#page-2-0) and mismatch between the  $R_{INT}$  and  $R_{FB}$  resistors on the positive (non-inverting) and negative (inverting) branches of the internal amplifier network.

As stated previously, matching of resistors ratios is very small, but can be conservatively approximated by device's typical gain error of ±0.25%. Using this information, one can simulate the ideal amplifier network and measure maximum  $I_{OS}$  by setting all resistors in one branch to +0.25% and in the other branch set to -0.25%. For  $V_{CM}$  = 16V,  $I_{OS}$  is 450µA. Since all resistors will have the same drift,  $I_{OS}$  drift will be fairly low and simply approximated as 10ppm/°C. If a one-point calibration is performed, then error from  $I_{OS}$  will be negated. Please contact TI support for more information if necessary.



Figure 6-1. Worst-Case I<sub>OS</sub> For Single-Stage CSA

For  $I_{B, CM ON}$ , the typical value is simply the jump in  $I_{B, CM}$  as shown in [Figure 2-2.](#page-2-0) Tolerance can be approximated as process variation. Drift can be deduced by  $I_{B, CM}$  versus temperature data plots in data sheet. For the INA185, the data sheet shows a 2µA change in I<sub>B, CM</sub> from -40°C to 125°C. Assume this value is 3µA and you can determine drift in ppm/°C as:

$$
I_{B, CM\ ON}\ Drit = \pm 10^6 \times \frac{\Delta I_{B, CM} \times 0.5}{\Delta T_A} \times \frac{1}{I_{B, CM\ ON}}\tag{17}
$$

Lastly temperature dependencies in  $V_S$  and especially  $V_{CM}$  need to be considered as these can add to the offset drift, which cannot be calibrated.

The calculated  $e_{EXT}$  values at 25 $^{\circ}$  and maximum ambient temperature are shown in Table 6-2.

Offset Values are Referred-to-Shunt (RTS) Using Worst-Case GEF at 125°C





Note that worst-case  $V_{OS, EXT}$  occurs when PV = -20%.

Table 6-3 shows offset values for both RTI and RTS along with the GEF used to convert them. The RTI values match the  $V_B$  measurement in simulation of the circuit as well shown in Figure 6-2.







**Figure 6-2. Simulation of Example at 125°C**





**Figure 6-3. Total Error Comparisons with One-Point Offset Calibration at 25°C**

<span id="page-14-0"></span>

# **7 Design Procedure for Input Resistance on Capacitively-Coupled Current Sense Amplifier**

When using  $R_{EXT}$  >100-Ω with the INA190 or similar CSA with capacitive-coupled input, the procedure for determining the error is outlined in the following.

- 1. Based upon the maximum possible operating temperature, determine the input differential resistance  $(R_{\text{DIFF}})$ values at the nominal operating temperature (25°C) and maximum ( $T_{A, hich}$ ) and minimum temperatures  $(T_{A, low})$ .
	- a. This data plot (for example, [Figure 1-2\)](#page-1-0) can be available in the data sheet.
- 2. Calculate GEF for each temperature using the equation provided in data sheet as shown in Equation 18. a. Calculate  $E_{G, EXT}$  at each temperature as 1-GEF
- 3. Using values from step 2, calculate the drift in external loading gain error using Equation 19.
	- a. Note  $E_G$   $_{FXT}$  can decrease significantly at increasing temperatures so try to choose two values that correspond linearly the best with the roll-off in gain.
- 4. The new typical circuit gain at 25°C needs to be calculated using [Equation 3.](#page-3-0)

$$
GEF_{Capacitive-coupled} = \frac{R_{DIFF}}{R_{DIFF} + R_{SH} + 2 \times R_{EXT}} \tag{18}
$$

$$
E_{G\ Drift, \ EXTHigh-Nominal} = \frac{E_{G\ EXT, \ TA, High} - E_{G\ EXT, \ T_A, Nominal}}{T_A, High - T_A, Nominal} \times 10^6
$$
\n
$$
E_{G\ Drift, \ EXT_{Low- Nominal} = \frac{E_{G\ EXT, \ T_A, Low} - E_{G\ EXT, \ T_A, Nominal}}{T_A, Low - T_A, Nominal} \times 10^6
$$
\n(19)

# **7.1 Bench Verification of Input eEXT for Capacitively-Coupled Current Sense Amplifiers**

Determining input resistive loading error, especially for offset and drift is not currently a theoretical procedure and does require a bench verification due to the highly non-linear impedance of internal switching capacitors. The general procedure is straightforwad, in that the engineer can sweep  $V_{\text{OUT}}/V_{\text{IN}}$  over temperature without and with  $R_{FXT}$  (and a stabilizing  $C_{DIFF}$ ) and calculate total gain, offset and drift errors using standard linear interpolation. The error generated solely from  $R_{EXT}$  is calculated by calculating the change in total errors.

There are two methods a designer can use to understand the realistic error to expect.

## **Method 1 - Sweep Input with Precision Differential Voltage Source**

This method requires emulating the shunt resistor's voltage drop  $(V_{SHIINT})$  with a precision DC voltage source  $(V_{\text{IN}})$  capable of accurately driving milli-volts. Additionally, this source can have a 4-wire force and sense capability.

While this can seem the simplest approach, there is a downside concerning the inductance of long input wires going into the CSAs input pins (IN+ and IN-). As noted, a capacitively-coupled CSA can have complex capacitive switching network at it front end. These capacitors can be constantly charging and discharging with current supplied from the bus. The average current is small (nano-Amps), but the peak transient input bias current can be larger.

Any input inductance can load down these capacitors and create delays causing significant device error. Usually this is not a problem because the input traces from  $R_{\text{SHUNT}}$  to CSA input pins is not long enough to generate significant inductance. Additionally, inductive loading can be negated with a small input differential capacitor  $(C_{\text{DIFF}})$  as shown in [Figure 4-1](#page-4-0).

Overall, if using this method make sure the  $V_{IN}$  source is a 4-wire force and sense connection and that CSA has a  $C_{\text{DIFF}}$  > 1-nF potentially more depending on how long cabling is and how high the ambient temperature is.

## **Method 2- Sweep Input with a Monitored Current Source and Calibrated Shunt Resistor**

This method is the actual sensing of current across a soldered down shunt resistor with soldered down CSA circuit. It requires more effort up front, but can achieve more precise results. Also, it does not require negating input pin cable inductance because input traces can be small on realistic PCB.



The downsides with this method is it requires knowing the approximate shunt resistor  $(R<sub>SHUNT</sub>)$  to be used in system and being able to solder it onto the CSAs EVM or prototype system PCB.

Another challenge is having an accurate ammeter to measure load directly. If testing requires larger currents, consider using precision shunt that is temperature controlled and monitored with accurate voltmeter.

Load current can be controlled simply with a variable resistor or rheostat pulling current from a stand voltage source emulating the bus voltage. Electric current sources, which can be more precise, can be used if desired and available

One convenient advantage with this method is that the shunt resistor does not need to be measured for gain calibration because external loading error ( $e_{EXT}$ ) is delta in error from  $R_{EXT}=0$ -Ω to  $R_{EXT}>0$ -Ω.

If engineer chooses to measure R<sub>SHUNT</sub> over temperature for gain calibration and accurate understanding of circuit error, then  $R_{\text{SHUNT}}$  can first be soldered down onto the PCB and measured with a precision 4-wire, Ohm-meter at the nominal, maximum, and minimum operating system ambient temperatures. Care needs to be taken for measurements to settle. Additionally, any resistance in parallel (including the CSA can be removed/ negated) so the R<sub>SHUNT</sub> measurement is not affected. Once R<sub>SHUNT</sub> is calibrated, you can negate its tolerance by calculating .

 $V_{IN} = R_{SHUNT.~CAL} \times Load_{Measured}$  (20)

# <span id="page-16-0"></span>**8 Design Procedure for Input Resistance at CSA Reference Pins**

When CSAs have external input resistance at the REF pin, the designer must confirm that the reduced dynamic range of CSA output can still meet system requirements. This requires considering all possibilities of resistor tolerance, CSA process variation, bus voltage variation, and supply voltage (Vs), if using a resistor divider of Vs pin.

- 1. Before the analysis, understand what are the maximum and minimum bounds of the linear operating range of  $V<sub>OUT</sub>$ , as well as, how are these bounds are further constrained by device output voltage noise.
	- a.  $V_{\text{OUT, MAX}} = V_{\text{OUT, MAX linear}} V_{\text{OUT, noise pk-pk}}/2$
	- b.  $V_{\text{OUT, MIN}} = V_{\text{OUT, MIN}}$  linear  $+ V_{\text{OUT, noise pk-pk}}/2$ 
		- i. Usually  $V_{OUT, MAX linear}$  can be 100mV below output's swing to supply voltage.
		- ii. Usually  $V_{\text{OUT, MIN linear}}$  can be 100mV above output's swing to ground.
- 2. For each PV corner, examine all 4 possible worst-case Ra and Rb combination at maximum temperature swing (assume the PV corner can have both PTC and NTC).
	- a. Calculate the designed for reference voltage value  $V_{REF\_\mathcal{X}}~=~~V_S~\times~\left.R_a\right|\left.R_b\right.$
	- b. Calculate the effective input resistance  $(Rx = Ra||Rb)$ .
- 3. For each combination, calculate the effective reference voltage ( $V_{REFE}$ <sub>EFFECTIVE</sub>) using Equation 21 as shown outlined in the following *[Driving Voltage Reference Pins of Current-Sensing Amplifiers](https://www.ti.com/lit/pdf/sboa551)*, application note.
	- a.  $V_{OUT\_error}$  =  $m\left(-V_{REF,x}$  +  $V_{CM}$  +  $^{VDIFF}/2$  $V_{REF, EFFECTIVE Predicted}$  =  $V_{REF,x}$  +  $V_{OUT\_error}$ (21)
	- b. Note that if the CSA has external input resistors at input pins, then  $R_{EXT}$  needs to be added to in-series with  $R_{INT}$ .

c. Assume maximum possible  $V_{CM}$ .

- 4. Determine the worst-case maximum and minimum  $V_{REFE}$  EFFECTIVE
	- a. Maximum V<sub>REF\_EFFECTIVE</sub> usually occurs at -PV, -PV\_TC, minimum Ra, and maximum Rb.
	- b. Minimum  $V_{REF}$  **EFFECTIVE usually occurs at +PV, +PV\_TC, maximum Ra, and minimum Rb.**
- 5. Confirm the circuit's measurable dynamic range at maximum temperature swing. For each PV corner:
	- a. Determine the worst-case total RTI offset  $\pm (V_{OS, EXTRTI} + V_{OS, RTI})$
	- b. Calculate the device's worst-case gain error.
	- c. Calculate the worst-case V<sub>OUT</sub> at no load (V<sub>OUT 0A</sub>) with V<sub>OUT 0A</sub> =  $\pm$ V<sub>OS, total</sub>\*Gain + VREF\_EFFECTIVE, MAX/MIN
		- i. Usually the maximum  $V_{\text{OUT OA, MAX}}$  occurs at minimum PV/PV\_TC, maximum  $V_{\text{OS, Total}}$ , and maximum  $V_{REFEF}$  EFFECTIVE.
		- ii. Usually the minimum V<sub>OUT 0A, MAX</sub> occurs at maximum PV/PV\_TC, minimum V<sub>OS, Total</sub>, and minimum V<sub>REF</sub> EFFECTIVE.
	- d. Determine measurable current assuming a differential measurement of output
		- i.  $I_{\text{Measureable, low}} = (V_{\text{OUT, MIN}} V_{\text{OUT\_0A, MIN}})/(Gain_{\text{Typical}} * R_{\text{SHUNT}})$
		- ii.  $I_{\text{Measurable, high}} = (V_{\text{OUT, MAX}} V_{\text{OUT 0A, MAX}})/(Gain_{\text{Typical}} * R_{\text{SHUNT}})$



# <span id="page-17-0"></span>**9 Input Resistance Error Test with INA185 Over Temperature**

A characterization of the INA185A4 was performed to quantify and verify the error generated by input resistance at both input pins ( $e_{EXT}$ ) and reference pins ( $e_{REF,EXT}$ ) over temperature.

## **9.1 Schematic**

An INA185A4 evaluation module (EVM) was used along with high temperature cables, precision instrumentation, and an insulated temperature chamber. The test setup is shown in Figure 9-1.



**Figure 9-1. Test Setup to Measure External Resistance Error with INA185A4**

## **9.2 Methods**

The input resistors chosen for the input pins ( $R_{EXT1}$  at IN+ and  $R_{EXT2}$  at IN-) were 110 $\Omega$  resistors along with a differential 1nF input capacitor ( $C_{\text{DIFF}}$ ). For the references pins, an approximate 150mV reference voltage was generated with a 49.9kΩ (Ra) and 1.5kΩ (Rb) resistor divider off the V<sub>S</sub> pin as shown in Table 9-1.





<span id="page-18-0"></span>

Errors generated from input resistance and reference resistance were distinguished from each other by measuring differential output along with monitoring reference voltage simultaneously.

Input-Output sweeps were run on the EVM at -40°C, 25°C, and 125°C ambient temperatures first with  $R_{EXT} = 0\Omega$ and then with R<sub>EXT</sub> = 110Ω. V<sub>OUT</sub> was monitored to remain with device's linear output operating region. Linear output region for INA185 is defined at 0.75V <  $V_{OUT}$ <4.9V. Additionally, at 125°C, the  $V_{CM}$  was swept to measure common-mode rejection (CMR).

Data analysis begins by calculating the total shunt voltage gain using a best-fit line method on all of the  $V_{\text{OUT}}$  Differential and the  $V_{\text{DIFF}}$  values within the designated linear output region. For each  $V_{\text{DIFF}}$ , an input offset is calculated using linear interpolation with the calculated gain. The final  $V_{OS}$  chosen for analysis is the average of all individual offsets pertaining to designated linear output region.

Exact external input resistance errors ( $E_{G, ET}$ ,  $V_{OS, EXT}$ ,  $E_{G, DRIF, EXT}$ ,  $V_{OS, Drift, EXT}$ , and CMRR<sub>EXT</sub>) quantified by simply calculating the error difference with and without input resistances.

The loading error to the REF pin ( $e_{REF,EXT}$ ) is also considered. The measured reference pin ( $V_{REF\_EFFECTIVE}$ ) is compared against a theoretical value using [Equation 21](#page-16-0) from related *[Driving Voltage Reference Pins of](https://www.ti.com/lit/pdf/sboa551)  [Current-Sensing Amplifiers](https://www.ti.com/lit/pdf/sboa551)*, application note. Review this note for more understanding on how these equations were derived.

Errors are compared against a predicted model that uses equations found in [Section 6](#page-6-0).

## **9.3 Theoretical Model**

Data is checked against a potential theoretical model of the device using equations from [Section 6](#page-6-0). Although, nearly impossible to back calculate internal device parameters from measured data given many possible combination of error sources, data checks were performed here to verify equations.

First, circuit conditions and all resistors tolerances and drifts were set as shown in Table 9-2.



**Table 9-2. Circuit and Device Parameters for Prediction Model**

Next, theoretical values of resistors and constants were calculated for each temperature. All values were calculated using equations from [Section 6.](#page-6-0) The total predicted gain (G<sub>Total, predicted</sub>) was calculated by multiplying the GEF of modeled internal resistors and the measured device gain. Note that the GEF found in Equation 22 was used.

$$
G_{Total, predicted} = \left(Gain_{CSA, Measured} = \frac{R_{FB}}{R_{INT}}\right) \times GEF
$$
\n(22)

#### **Table 9-3. Prediction Model Resistors and Constants Over Temperature**





#### **Table 9-3. Prediction Model Resistors and Constants Over Temperature (continued)**

<span id="page-19-0"></span>

Lastly, the prediction model was finished by calculating variable external resistances at the REF pin. Error constants c and m are dependent upon  $R_{EXT}$  and thus two values are calculated for each  $R_{EXT}$ . The parameters here have the same terminology and follow the same equations as this *[Driving Voltage Reference Pins of](https://www.ti.com/lit/pdf/sboa551)  [Current-Sensing Amplifiers](https://www.ti.com/lit/pdf/sboa551)*, application note.



## **Table 9-4. Prediction Model Parameters for eEXT, REF**

Note that this theoretical models only assume linear resistor temperature coefficients; when realistically the temperature coefficient can be highly non-linear. Thus the model was tuned to get best matching to the data for change in ambient temperature from 25°C to 125°C.

c (R<sub>EXT</sub> = 110Ω) 0.002909224 0.0029033385 0.002933385 m (R<sub>EXT</sub> = 110Ω)  $\vert$  0.002900785  $\vert$  0.002910223  $\vert$  0.002924806

### **9.4 Data for INA185A4 with 110Ω Input Resistors**

 $V_{CM}$  = 12V



#### **Table 9-5. Input-Output Sweep with INA185A4 and REXT = 0Ω**





 $V_{CM}$  = 12V

<span id="page-20-0"></span>

#### $Table 9-7$  Input-Output Sweep with INA185A4 and R<sub>→z</sub> = 110Ω

### Table 9-8.  $V_{OUT}$  versus  $V_{CM}$  with INA185A4 and  $R_{EXT}$  = 110Ω at 125°C



#### *9.4.1 Data Calculations*

#### Table 9-9. Typical (Nominal) Shunt Voltage Gain vs. R<sub>EXT</sub> at IN+ and IN-



#### **Table 9-10. Calculated Total Gain Using Best Fit Line**



### $E_G$  is calculated relative to the typical gain as shown in Table 9-11

#### **Table 9-11. Calculated Total Gain and Offset Error**



### Table 9-12. Calculated and Predicted External Input Resistance Error ( $e_{\text{EXT}}$ )







<span id="page-21-0"></span>

### **Table 9-13. Calculated Total Gain and Offset Error Drift**



### Table 9-14. Calculated and Predicted External Input Resistance Error Drift (e<sub>EXT Drift</sub>)



# Table 9-15. Measured Input Offset and Calculated V<sub>OS, EXT</sub> over V<sub>CM</sub> at 125°C



### **Table 9-16. Measured Input CMRR and Calculated CMRREXT at 125°C**



### **Table 9-17. Measured and Predicted VOS, EXT over VCM at 125°C**



 $V_{\text{SENSE}}$  = 23-mV,  $T_A$  = 125°C

## **Table 9-18. V<sub>REF\_EFFECTIVE</sub>** (V) over V<sub>CM</sub>



<span id="page-22-0"></span>

**Table 9-19. VREF, EFFECTIVE (V) over Temperature**

## **9.5 Analysis**

The determined data nicely follow the predictive model and thus easily fall within maximum possible error, which is unlikely to measure.

One notable difference between measurements and predictions occur at -40°C as seen with gain errors in [Table 9-12](#page-20-0) and [Table 9-14](#page-21-0). This can mostly be because the model's parameters assumed linear temperature coefficients; however,  $R_{EXT}$  can easily have non-linear, even parabolic, temperature coefficients that changed polarity going cold. Best efforts was made to get lowest prediction errors and future efforts can employ non-linear temperature coefficients. Tradeoffs were made so that prediction model at least matched the 125°C range.

The other high prediction error occurred with the  $V_{OS, EXT}$  at  $V_{CM}$ =0-V in [Table 9-17.](#page-21-0) This can be a result of the change in I<sub>B, CM</sub> slope when  $V_{CM}$  <  $V_S$ , which can be seen in [Figure 2-2](#page-2-0). If accurate leakage input bias current is required at this level please post an inquiry on our public forum for more information.



# <span id="page-23-0"></span>**10 Input Resistance Error Test with INA191 Over Temperature**

A characterization of the INA191A4 was performed to quantify and verify the error generated by input resistance at input pins ( $e_{EXT}$ ).

### **10.1 Schematic**



**Figure 10-1. Test Setup to Measure External Resistance Error with INA191A4EVM**

For testing, non-temperature compliant components were removed.

<span id="page-24-0"></span>



**Figure 10-2. INA191A4EVM Schematic**

### **10.2 Methods**

EVM shunt resistor pads were populated a 1Ω shunt resistor, which was measured with a 4-wire force and sense Ohm meter inside a temperature chamber at -40°C, 25°C, and 125°C. The input resistors chosen for the input pins (R<sub>EXT1</sub> at IN+ and R<sub>EXT2</sub> at IN-) were 2.2kΩ resistors along with a differential 10nF input capacitor.



#### **Table 10-1. BOM for INA191A4EVM Modifications**

Input-Output sweeps were run on the EVM at -40°C, 25°C, and 125°C ambient temperatures first with R<sub>EXT</sub> = 0 $\Omega$ and then with  $R_{EXT}$  = 2.2kΩ. Load current was controlled by a power rheostat and monitored a precision, 8-digit Ammeter. Approximate current sweep range was from 0.48 $\mu$ A to 240mA. V<sub>OUT</sub> was measured by a >5.5 -digit voltmeter and monitored to remain with device's linear output operating region. Linear output region for INA191 was defined at  $0.9V < V_{\text{OUT}} < 4.9V$ .

Data analysis began by calculating the total shunt voltage gain using a 2-point line method on all of the V<sub>OUT</sub> and the V<sub>DIFF</sub> values within the designated linear output region. For each V<sub>DIFF</sub>, an input offset is calculated using linear interpolation with the calculated gain. The final  $V_{OS}$  chosen for analysis was the average of all individual offsets pertaining to designated linear output region. Data analysis using gain calculated from a best-fit line was also performed as a check for any major dissimilarities.

Exact external input resistance errors (E<sub>G, EXT</sub>, V<sub>OS, EXT</sub>, E<sub>G DRIFT, EXT</sub>, V<sub>OS Drift, EXT</sub>) quantified by simply calculating the error difference with and without input resistances. Note that the same  $e_{EXT}$  error can be calculated even if shunt resistor was not calibrated.



# <span id="page-25-0"></span>**10.3 Theoretical Model**

For CSA with capacitive-coupled inputs, the best way to calculate error is to determine  $R_{\text{DIFF}}$  at each operating temperature using data sheet plots and then use the GEF equation to understand how gain can attenuate. [Section 7](#page-14-0).

A theoretical model was considered using parameters below. The  $R_{\text{DIFF}}$  values from the data sheet and the device's measured gain (G<sub>Device, measured</sub>) at each temperature were entered. The predicted total gain  $(G<sub>Total</sub>, <sub>predicted</sub>)$  was calculated using:

 $G_{Total, predicted} = (Gain_{CSA, Measured}) \times GEF$  (23)



# **Table 10-2. Prediction Model Parameters Over Temperature**

### **10.4 Data for INA191A4 With 2.2kΩ Input Resistors**

### **Table 10-3. Calibrated RSHUNT on INA191A4EVM Over Temperature**



#### **Table 10-4. Input-Output Sweep with INA191A4 and REXT = 0Ω**





#### Table 10-5. Input-Output Sweep with INA191A4 and R<sub>EXT</sub> = 2.2kΩ and 10nF C<sub>DIFF</sub>

#### *10.4.1 Data Analysis*

#### Table 10-6. Typical (Nominal) Shunt Voltage Gain vs. R<sub>EXT</sub> at IN+ and IN-



#### **Table 10-7. Calculated and Predicted Total Gains**



#### **Table 10-8. Calculated Gain and Offsets Errors**



#### **Table 10-9. Calculated Gain and Offset Drift**





<span id="page-27-0"></span>

#### **Table 10-11. Calculated and Predicted External Input Resistance Error Drift (eEXT, Drift)**



### **10.5 Analysis**

The INA191 performed very closely as expected according to the theoretical calculations. Prediction errors for E<sub>G, EXT</sub> (approximately 0.06%) and E<sub>G, EXT Drift</sub> (approximately 0.25ppm/°C) were precise and show little change over temperature. These errors were small enough that the errors can come simply from variation in  $R_{EXT}$  and/or ammeter accuracy.

E<sub>G, Drift</sub> performance for INA191 was outside of its specification of 7ppm/°C, although this does not affect analysis primarily because the critical value of measurement was  $e_{EXT}$ , which is a delta measurement with and without  $R_{\text{EXT}}$ . Certainly, the most probably reason for this large gain error drift was an imperfect calibration of the shunt resistor.

 $V_{OS, \text{EXT}}$  was reasonable at around 2.4µV at 125°C, but  $V_{OS, \text{EXT} \text{Drift}}$  was significant at -45nV/°C when increasing temperature to 125°C. As expected,  $V_{OS, EXT\, Drift}$  reduces and flips polarity to 16.9nV/°C when decreasing temperature. Further efforts to reduce this drift can by increasing  $C_{\text{DIFF}}$ .

Considered that the theoretical model used typical  $R_{\text{DIFF}}$  values over temperature, yet performance was just below model boundaries. This indicates that for future designs, sufficient margin can be established to understand worst-case gain error. Downshifting (or reducing) the  $R_{\text{DIFF}}$  curve by 30% can provide ample margin.

<span id="page-28-0"></span>

# **11 Derivation of VOS, EXT for a Single Stage Current Sense Amplifier (CSA)**



This derivation assumes a single-stage, linear CSA. Derivation first begins by determining  $V_B$  (bias voltage across bias resistor) when load ( $I_L$ ) is 0A as this is essentially  $V_{OS, EXT RTI}$ . Then this is divided by gain error factor (GEF) to get the referred-to-shunt offset error ( $V_{OS, \,EXT\,RTS}$ ). Note that this derivation also requires a more specific equation for GEF which assumes that the  $R_{EXT}$  value at each pin can be different.

Let 
$$
{}^{I}OS_{/2} = I_{OS2}
$$
  
\nLet  $R_{FB} + R_{INT} = R_{FI}$   
\nLet  $I_{L} = 0 - A$   
\n(1)  $I_{SH} - I_{N} - I_{L} = 0$   
\n(2)  $I_{P} - I_{X} - I_{B} - I_{CM, ON} = 0$   
\n(3)  $I_{N} - I_{Y} + I_{B} - I_{CM, ON} = 0$   
\n(4)  $I_{Y} + I_{OS2} - I_{FB} = 0$   
\n(5)  $I_{X} - I_{OS2} - I_{REF} = 0$   
\n(6)  $V_{CM} - I_{SH}R_{SH} - I_{N}R_{F2} - I_{FB}R_{FI} - V_{OUT} = 0$   
\n(7)  $V_{CM} - I_{P}R_{EXT1} - I_{REF}R_{FI} - I_{FB}R_{FI} - V_{REF} = 0$   
\n(8)  $V_{CM} - I_{REF}R_{INT} + I_{FB}R_{INT} = 0$   
\n(9)  $V_{OUT} = V_{REF} + V_{B}R_{INT}$   
\n(10)  $V_{SH} - I_{P}R_{EXT1} - V_{B} + R_{EXT2}I_{N} = 0$ 

(4) into (3) and (5) into (2)

$$
I_P = I_{CM, ON} + I_B + I_{OS2} + I_{REF}
$$
  
\n
$$
I_N = I_{CM, ON} - I_B - I_{OS2} + I_{FB}
$$
\n(25)

(2) into (7)

$$
I_{REF} = \frac{V_{CM} - V_{REF} - R_{EXT1}(I_{CM, ON} + I_B + I_{OS2})}{R_{FI} + R_{EXT1}}
$$
(26)



(7) into (8)

$$
I_{FB} = \frac{V_{CM} - V_{REF} - R_{EXT1}(I_{CM, ON} + I_B + I_{OS})}{R_{FI} + R_{EXT1}} - \frac{V_B}{R_{INT}} \tag{27}
$$

(1), (3), and (9) into (6).

$$
V_{BUS} - V_{REF} - V_{B}(R_{FB}/R_{INT}) + V_{B}(R_{SH} + R_{EXT2})/R_{B} - (I_{CM} - I_{OS2})(R_{SH} + R_{EXT2}) - I_{FB}(R_{FI} \t(28) + R_{SH} + R_{EXT2}) = 0
$$

(8) into (6). Solve for  $V_B$ 

Let 
$$
C_{EV} = \frac{R_{FI} + R_{SH} + R_{EXT2}}{R_{FI} + R_{EXT1}} = \frac{1 + \frac{R_{SH} + R_{EXT2}}{R_{FI}}}{1 + \frac{R_{EXT1}}{R_{FI}}}
$$
 (29)  
\n
$$
V_B = \frac{\left(V_{REF} - V_{BUS}\right)\left(1 - C_{EV}\right) + I_{B,CM~ON}\left(R_{SH} + R_{EXT2} - R_{EXT1}C_{EV}\right) - \frac{I_{OS}}{2}\left(R_{SH} + R_{EXT2} + R_{EXT1}C_{EV}\right)}{1 + \left(R_{SH} + R_{EXT2}\right)\left(R_{INT} + \frac{1}{R_{BIAS}}\right) + \frac{R_{EXT1}C_{EV}}{R_{BIAS}}}
$$

Determine Gain Error Factor when  $R_{\sf EXT1}$  does not equal  $R_{\sf EXT2}$ . You can simply remove I $_{\sf CM, ON}$ , I $_{\sf OS}$  sources, and set V<sub>CM</sub> and V<sub>REF</sub> sources to 0V as these only affect the offset. Gain is constant throughout operational V<sub>CM</sub>.

(5) into (2)

Let 
$$
I_{CM, ON}
$$
 and  $I_{OS} = 0$   
Let  $V_{CM} = V_{REF} = 0$   
 $I_P = I_B + I_{REF}$  (30)

(2) into (7)

$$
I_{REF} = \frac{0 - 0 - R_{EXT1}(I_B + 0 + 0)}{R_{FI} + R_{EXT1}}
$$
\n(31)

(2), (8) into (10).

$$
V_{SH} - V_B - I_B (R_{EXT} + R_{EXT2}) - I_R R_{EXT1} + I_R R_{EXT2} - V_B R_{EXT2} / R_{INT} = 0
$$
\n(32)

(7) into (10). Solve for  $V_B/V_{SH}$  = GEF

Let 
$$
C_{EG} = \frac{R_{EXT1}}{R_{FI} + R_{EXT1}}
$$
\n
$$
\frac{V_B}{V_{SH}} = GEF = \frac{1}{\left(1 + \frac{R_{EXT2}}{R_{INT}}\right) + \frac{R_{EXT1} + R_{EXT2}}{R_B} - \frac{C_{EG}(R_{EXT1} - R_{EXT2})}{R_B}}
$$
\n
$$
V_{OS, \,EXT \,RTS} = \frac{V_{OS, \,EXT \,RTI}}{GEF}
$$
\n(33)

<span id="page-30-0"></span>

# **12 Summary**

The operational principles and equations for single-stage linear and capacitive-coupled CSAs match up with simulation and test data over temperature. True worst-case error might be statistically small, but are large enough to prompt potential one-point offset calibrations.

Also granted the right applications, using a resistor divider to set  $V_{REF}$  can provide substantial system and cost benefits.

# **13 References**

• Texas Instruments, *[Driving Voltage Reference Pins of Current-Sensing Amplifiers](https://www.ti.com/lit/pdf/sboa551)*, application note.

## **IMPORTANT NOTICE AND DISCLAIMER**

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](https://www.ti.com/legal/terms-conditions/terms-of-sale.html) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2024, Texas Instruments Incorporated